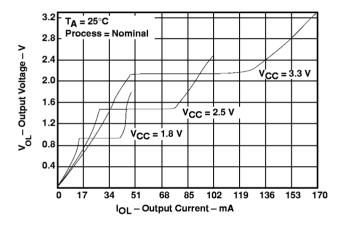
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- Member of the Texas Instruments Widebus™ Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- DOC™ (Dynamic Output Control) Circuit Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}

- Over-Voltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- I_{off} Feature Supports Partial Power-Down Mode Operation
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and Thin Very Small-Outline (DGV) Packages

description

A Dynamic Output Control (DOC) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, AVC Logic Family Technology and Applications, literature number SCEA006, and Dynamic Output Control (DOCTM) Circuitry Technology and Applications, literature number SCEA009.



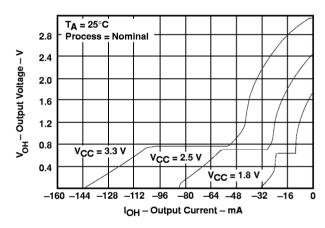


Figure 1. Output Voltage vs Output Current

This 16-bit bus transceiver and register is operational at 1.5-V to 3.6-V V_{CC} , but designed specifically for 1.65-V to 3.6-V V_{CC} operation.

The SN74AVCH16646 can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 2 illustrates the four fundamental bus-management functions that can be performed with the SN74AVCH16646.



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description (continued)

Output-enable (\overline{OE}) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port can be stored in either register or in both. The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. DIR determines which bus receives data when \overline{OE} is low. In the isolation mode (\overline{OE}) high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and may be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

DGG OR DGV PACKAGE

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74AVCH16646 is characterized for operation from -40°C to 85°C.

terminal assignments

DGG OR DGV PACKAGE (TOP VIEW)									
4 DID H	, U	EC	10E						
1DIR [1 0	56	_						
1CLKAB			1CLKBA						
1SAB		53] 1SBA						
GND [] GND] 1B1						
1A1 [1A2 [1B2						
		50							
V _{CC}] V _{CC}] 1B3						
1A3 [1A4 [48							
1A4 [1B5						
GND [GND						
1A6			1B6						
1A7 [1B0 1B7						
1A7 [1B8						
2A1			2B1						
2A1 [2B1 2B2						
2A2 [2B3						
GND [39	E						
2A4			2B4						
2A5 [37							
2A6		36	=						
v _{cc} [22	35							
2A7 [34	- 00						
2A8 [2B8						
GND [GND						
2SAB			2SBA						
2CLKAB	27	30	2CLKBA						
2011 DIR		29							



SN74AVCH16646 16-BIT BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS SCES182 - DECEMBER 1998

FUNCTION TABLE

		INP	UTS			DATA	\ I/Os	OPERATION OR FUNCTION		
ŌĒ	DIR	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	OPERATION OR FUNCTION		
Х	Х	1	Х	Х	Х	Input	Unspecified [†]	Store A, B unspecified [†]		
Х	Χ	Χ	1	Χ	Χ	Unspecified†	Input	Store B, A unspecified [†]		
Н	Х	1	↑	Χ	Х	Input	Input	Store A and B data		
Н	Х	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage		
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus		
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus		
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus		
L	Н	H or L	X	Н	Χ	Input	Output	Stored A data to B bus		

[†]The data-output functions may be enabled or disabled by various signals at $\overline{\sf OE}$ and DIR. Data-input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



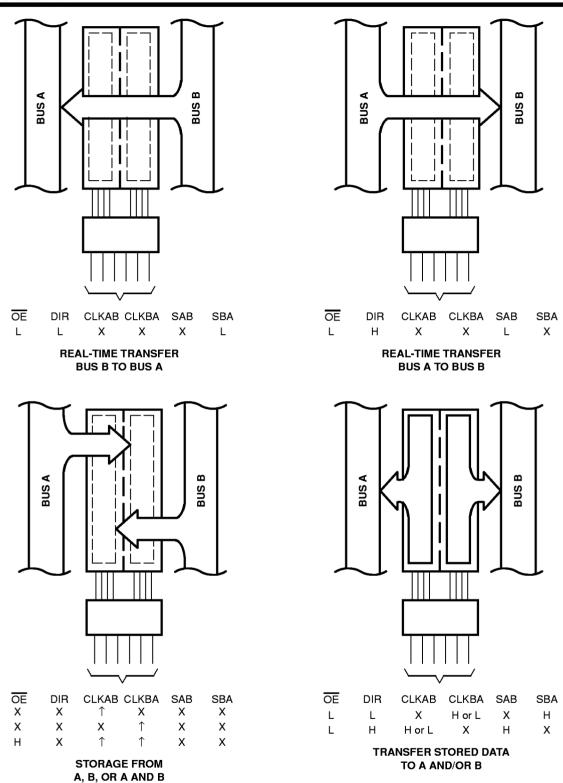
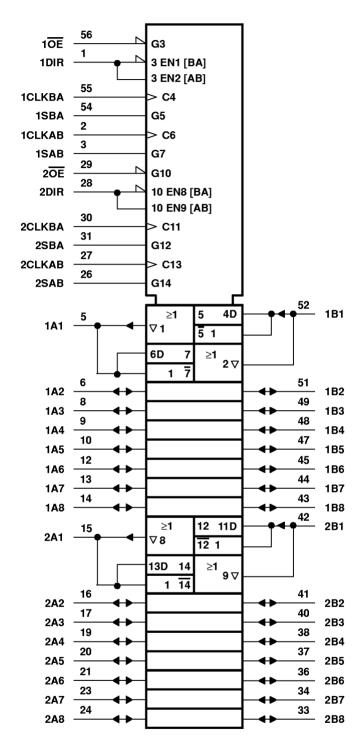


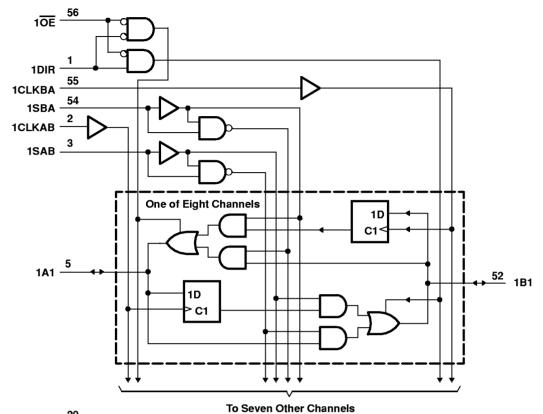
Figure 2. Bus-Management Functions

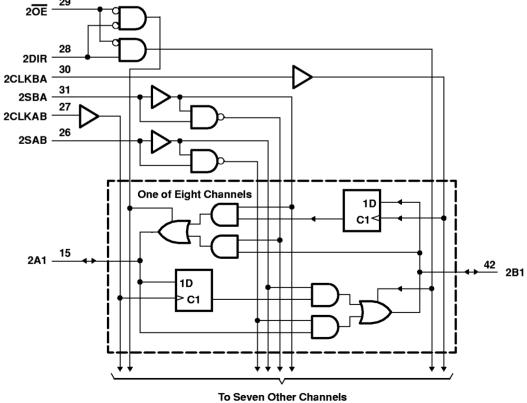


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.







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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I : Except I/O ports (see Note 1)	
I/O ports (see Notes 1 and 2)	0.5 V to V _{CC} + 0.5 V
Voltage range applied to any output in the high-impedance or pov	ver-off state, V _O
(see Note 1)	
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through each V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package	81°C/W
DGV package	86°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT				
V	Cumply voltage	Operating	1.65	3.6	V				
VCC	Supply voltage	Data retention only	1.2						
		V _{CC} = 1.2 V	V _{CC}						
V	Ligh level input valtage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}		\ _V				
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7]				
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2		1				
		$V_{CC} = 1.2 \text{ V}$		GND					
V	Low-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	V				
V _{IL}		V _{CC} = 2.3 V to 2.7 V		0.7	V				
		V _{CC} = 3 V to 3.6 V		8.0					
۷ _I	Input voltage	-	0	3.6	٧				
	Output valtage	Active state	0	Vcc	٧				
VO	Output voltage	3-state	0	3.6	٧				
		V _{CC} = 1.65 V to 1.95 V		-4					
IOHS	Static high-level output current‡	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-8					
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-12					
		V _{CC} = 1.65 V to 1.95 V		4					
lols	Static low-level output current‡	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		8	mA				
		V _{CC} = 3 V to 3.6 V		12					
Δt/Δν	Input transition rise or fall rate	V _{CC} = 1.65 V to 3.6 V		5	ns/V				
TA	Operating free-air temperature		-40	85	°C				

[‡] Dynamic drive capability is equivalent to standard outputs with I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}. See Figure 1 for V_{OL} vs I_{OL} and V_{OH} vs I_{OH} characteristics. Refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number **SCEA006**, and *Dynamic Output Control (DOC™) Circuitry Technology and Applications*, literature number **SCEA009**.

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAI	METER	TEST CON	DITIONS	vcc	MIN	TYP	MAX	UNIT	
		I _{OHS} = -100 μA		1.65 V to 3.6 V	V _{CC} -0	.2			
V		$I_{OHS} = -4 \text{ mA},$ V	IH = 1.07 V	1.65 V	1.2			v	
VOH		$I_{OHS} = -8 \text{ mA},$ V	IH = 1.7 V	2.3 V	1.75			V	
		$I_{OHS} = -12 \text{ mA},$ V	i _H = 2 V	3 V	2.3				
		I _{OLS} = 100 μA		1.65 V to 3.6 V			0.2		
V		$I_{OLS} = 4 \text{ mA},$ V	IL = 0.57 V	1.65 V			0.45	٧	
v_{OL}		I _{OLS} = 8 mA, V	IL = 0.7 V	2.3 V			0.55	v	
		$I_{OLS} = 12 \text{ mA},$ V	IL = 0.8 V	3 V			0.7		
I _I Cor	ntrol inputs	V _I = V _{CC} or GND		3.6 V			±2.5	μΑ	
		V _I = 0.57 V		1.65 V	25				
I _{BHL} ‡		V _I = 0.7 V	2.3 V	45			μА		
		V _I = 0.8 V		3 V	75				
I _{BHH} §		V _I = 1.07 V		1.65 V	-25				
		V _I = 1.7 V	2.3 V	– 45			μΑ		
		V _I = 2 V		3 V	-75				
				1.95 V	200				
$^{I_{BHLO}^{\P}}$		$V_I = 0$ to V_{CC}		2.7 V	300			μΑ	
				3.6 V	500				
				1.95 V	-200				
^І внно [#]		V _I = 0 to V _{CC}		2.7 V	-300			μΑ	
БППО				3.6 V	-500				
loff		V _I = 0 or 3.6 V		0			±10	μΑ	
loz		V _O = V _{CC} or GND		3.6 V			±12.5	μΑ	
lcc		V _I = V _{CC} or GND,) = 0	3.6 V			40	μA	
				2.5 V		3		»E	
C _i Cor	ntroi inputs	$V_I = V_{CC}$ or GND		3.3 V		3		pF	
C. A -	Dd.a	V- V CND		2.5 V		10			
C _{io} A o	r B ports	$V_O = V_{CC}$ or GND		3.3 V		10		pF	

[†] Typical values are measured at T_A = 25°C.



[‡] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{II} max.

[§] The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

[¶] An external driver must source at least IBHLO to switch this node from low to high.

[#] An external driver must sink at least I_{BHHO} to switch this node from high to low.

^{||} For I/O ports, the parameter IOZ includes the input leakage current.

timing requirements over recommended operating free-air temperature range (unless otherwise

			V _{CC} =		V _{CC} =		V _{CC} =		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency								MHz
t _W	Pulse duration	CLKAB or CLKBA high or low							ns
t _{su}	Setup time	A before CLKAB↑ or B before CLKBA↑							ns
t _h	Hold time	A after CLKAB↑ or B after CLKBA↑							ns

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 3 through 6)

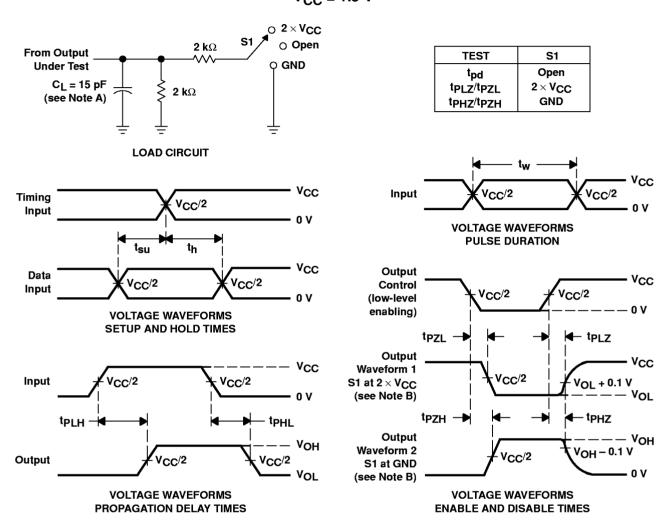
PARAMETER	FROM (INPUT)		V _{CC} = 1.5 V		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
	(INPOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}											MHz
	A or B	B or A									
t _{pd}	CLKAB or CLKBA	A or B									ns
	SAB or SBA										
t _{en}	ŌĒ	A or B									ns
^t dis	ŌĒ	A or B									ns
t _{en}	DIR	A or B									ns
^t dis	DIR	A or B									ns

operating characteristics, T_A = 25°C

noted) (see Figures 4 through 6)

	PARAMETER			TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT
ſ	<u> </u>	Power dissipation	Outputs enabled	C ₁ = 0, f = 10 MHz				ρF
	□pd	capacitance	Outputs disabled	$C_L = 0$, $f = 10 MHz$				ÞΓ

PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.5 V

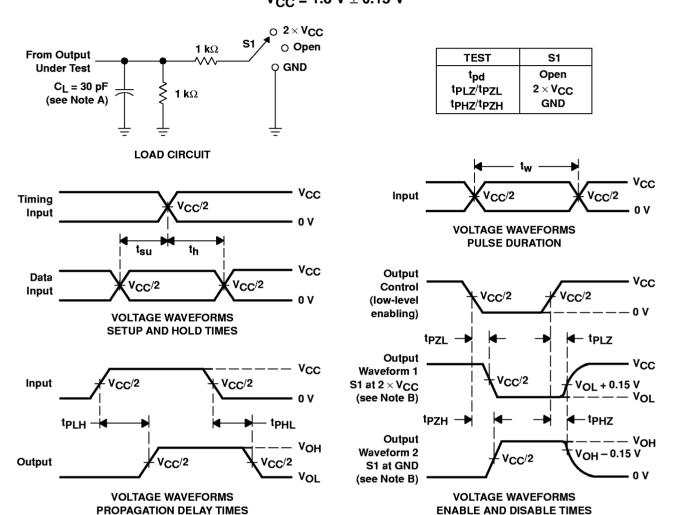


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



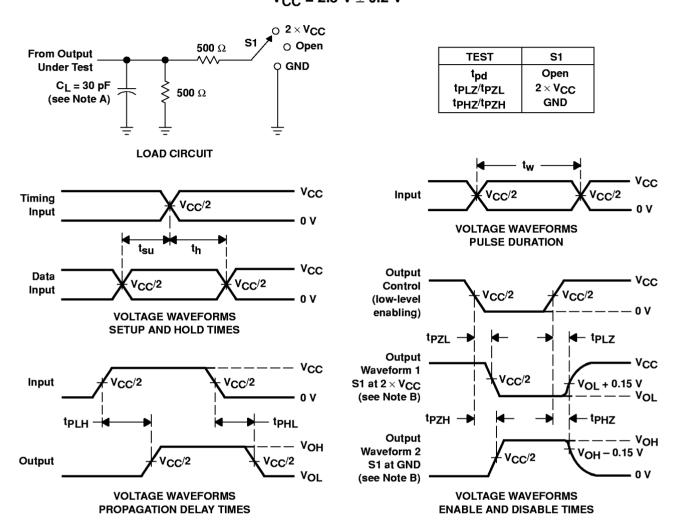
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$



- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_r \leq$ 2 ns, $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpl 7 and tpH7 are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 4. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 V \pm 0.2 V$



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq$ 2 ns, $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

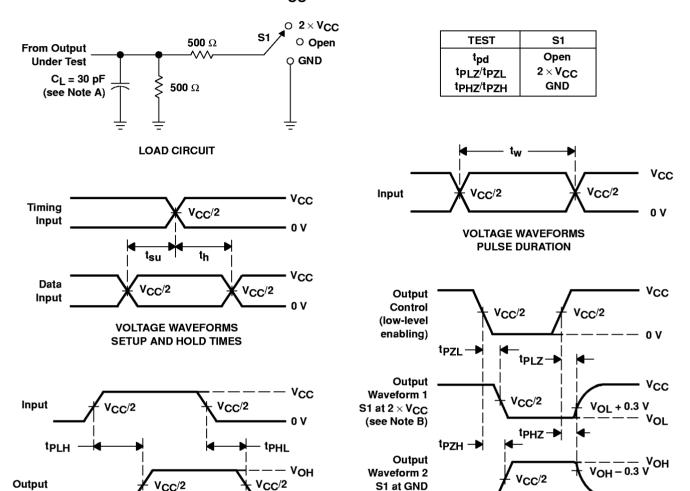
Figure 5. Load Circuit and Voltage Waveforms



VOLTAGE WAVEFORMS

ENABLE AND DISABLE TIMES

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

S1 at GND

(see Note B)

- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{r} \leq$ 2 ns, $t_{f} \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.

VOL

E. tpLz and tpHz are the same as tdis.

VOLTAGE WAVEFORMS

PROPAGATION DELAY TIMES

- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 6. Load Circuit and Voltage Waveforms

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